



Material Content Data Sheet



Sales Product Name	TLE42744E V50			Issued	27. September 2017			
MA#	MA000970666							
Package	PG-SSOP-14-2			Weight*	83.47 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.179	3.81	3.81	38086	38086
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		103	
	non noble metal	zinc	7440-66-6	0.034	0.04		413	
	non noble metal	iron	7439-89-6	0.689	0.83		8255	
wire	non noble metal	copper	7440-50-8	27.978	33.52	34.40	335192	343963
	noble metal	gold	7440-57-5	0.087	0.10	0.10	1044	1044
	encapsulation	organic material	carbon black	1333-86-4	0.096	0.12		1155
plastics		epoxy resin	-	4.434	5.31		53123	
	inorganic material	silicondioxide	60676-86-0	43.666	52.32	57.75	523151	577429
leadfinish	non noble metal	tin	7440-31-5	0.976	1.17	1.17	11695	11695
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9196	9196
glue	plastics	epoxy resin	-	0.388	0.46		4647	
	noble metal	silver	7440-22-4	1.164	1.39	1.85	13940	18587
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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